

RoHS Compliant Product

SOT-363

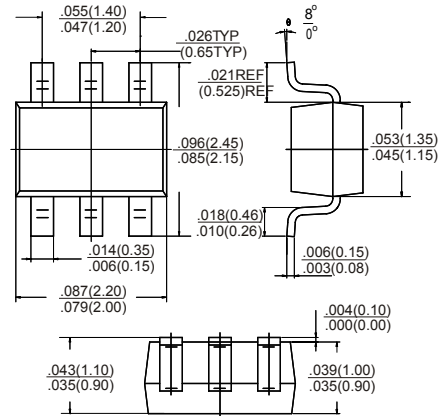
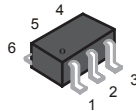
A suffix of "-C" specifies halogen & lead-free

**FEATURES**

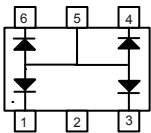
- Fast Switching Speed
- Ultra-Small Surface Mount Package
- High Conductance Power dissipation

**MECHANICAL DATA**

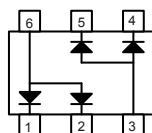
- Case: SOT-363, Molded Plastic
- Terminals: Solderable per MIL-STD-202, Method 208
- Polarity: See Diagrams Below
- Weight: 0.006 grams (approx.)
- Mounting Position: Any



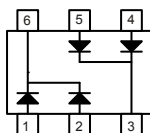
Dimensions in inches and (millimeters)



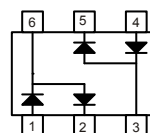
MMBD4448HAQW  
Marking: KA5



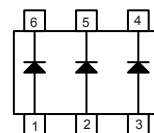
MMBD4448HADW  
Marking: KA6



MMBD4448HCDW  
Marking: KA7



MMBD4448HSDW  
Marking: KAB



MMBD4448HTW  
Marking: KAA

**MAXIMUM RATINGS** (T<sub>A</sub> = 25°C unless otherwise noted)

| Rating   | Symbol              | Value       | Unit |
|--|---------------------|-------------|------|
| Non-Repetitive Peak Reverse Voltage                | V <sub>RM</sub>     | 100         | V    |
| Peak Repetitive Reverse Voltage                    | V <sub>R(RM)</sub>  | 80          | V    |
| RMS Reverse Voltage                                | V <sub>R(RMS)</sub> | 57          | V    |
| Average Rectified out Current(Note 1)              | I <sub>o</sub>      | 250         | mA   |
| Forward Continuous Current (Note 1)                | I <sub>FM</sub>     | 500         | mA   |
| Thermal Resistance Junction to Ambient Air (Note1) | R <sub>thJA</sub>   | 625         | °C/W |
| Storage Temperature Range                          | T <sub>stg</sub>    | -55 to +150 | °C   |

Notes: 1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout

**ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted) (EACH DIODE)

| Characteristic  | Symbol          | Min  | Max  | Unit  |    |
|---|-----------------|--|------|-------|----|
| Reverse Breakdown Voltage (Note 2)  | V(BR)R          | 80   | ∅    | V     |    |
| Forward Voltage (Note 2)  | V <sub>F</sub>  | F=5.0mA                                    | 0.62 | 0.72  | V  |
|   |                 | I <sub>F</sub> =10mA                       | —    | 0.855 |    |
|   |                 | I <sub>F</sub> =100mA                      | —    | 1.0   |    |
|   |                 | I <sub>F</sub> =150mA                      | —    | 1.25  |    |
| Reverse Current (Note 2)  | I <sub>R</sub>  | V <sub>R</sub> =70V                        | —    | 100   | nA |
|   |                 | V <sub>R</sub> =75V, T <sub>j</sub> =150°C | —    | 50    | uA |
|   |                 | V <sub>R</sub> =25V, T <sub>j</sub> =150°C | —    | 30    | uA |
|   |                 | V <sub>R</sub> =20V                        | —    | 25    | nA |
| Total Capacitance V <sub>R</sub> =6V, f=1.0MHz  | C <sub>T</sub>  | —  | 3.5  | pF    |    |
| Reverse Recovery Time I <sub>F</sub> =I <sub>R</sub> =10mA, I <sub>rr</sub> =0.1X I <sub>R</sub> , R <sub>L</sub> =100 Ohms | t <sub>rr</sub> | —  | 4.0  | nS    |    |

Note 2. Short duration test pulse used to minimize self-heating.

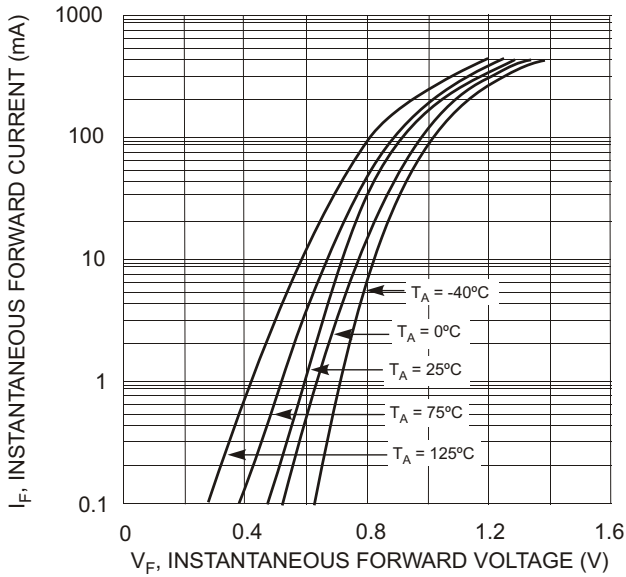


Fig. 1 Typical Forward Characteristics

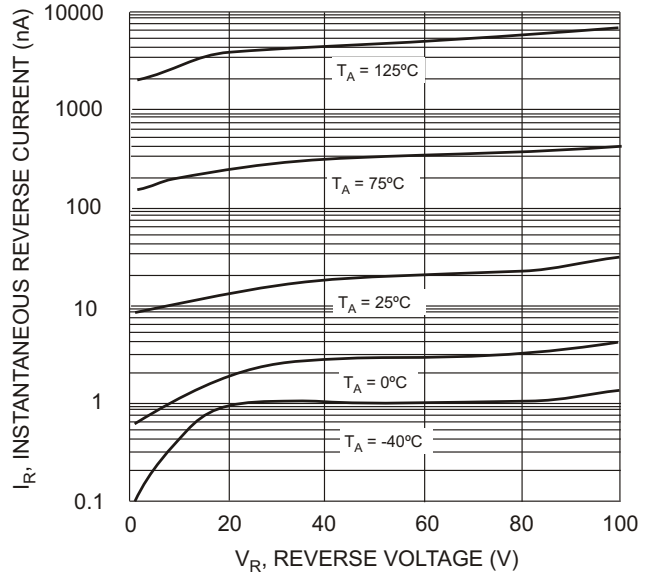


Fig. 2 Typical Reverse Characteristics

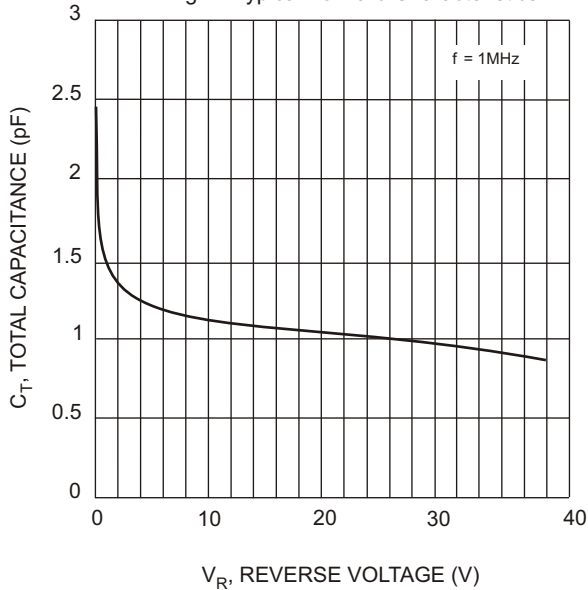


Fig. 3 Typical Total Capacitance vs. Reverse Voltage

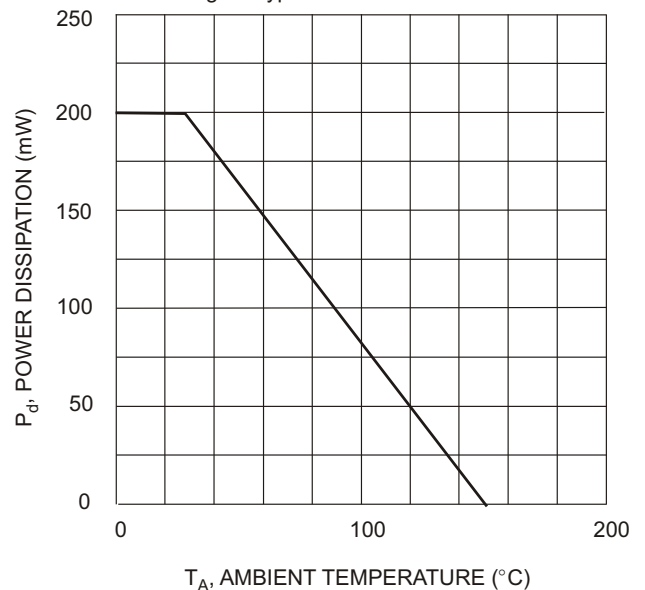


Fig. 4 Power Derating Curve, Total Package

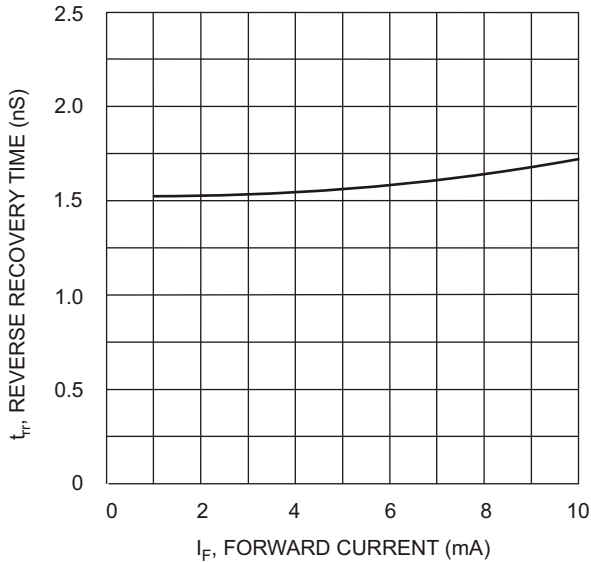


Fig. 5 Reverse Recovery Time vs Forward Current.